	<b>i</b> connection	tors <b>S</b>
	SPECIFICATI	ON
宏到	<b>太電子股份</b> 有	<b>f</b> 限公司
	桃園縣中壢市東園路	- 13 號
	No.13, Dongyuan Rd., Jhong	gli City,
	Taoyuan County 320, Taiwan	(R.O.C.)
	TEL: +886-3-463-28 FAX: +886-3-463-18	
SPEC. NO.: PS-515	39-XXXXX	REVISION: C
<b>PRODUCT NAME:</b>	0.5 mm PITCH ZIF BACK F	LIP FPC CONN.
	SMT R/A D/C TYPE	
<b>PRODUCT NO:</b>	51539 SERIES	
PREPARED:	CHECKED:	APPROVED:
ZHOUQUAN	BRAVE	FRANK
DATE: 2015/09/01	DATE: 2015/09/01	DATE: 2015/09/01

2010/10/31 TR-FM-73015L

ЛĊ	inectors		Aces P/N: 5	51539-XXXXX series	6
TITLE:	0.5 mm PITCH Z	IF BACK FL	IP FPC COI	NN. SMT R/A TYPE	
RELEASE	DATE: 2015/09/01	REVISION: C		ECN No: ECN-1509013	PAGE: 2 OF 13
1 2					
3	APPLICABLE DC	CUMENTS			4
4	REQUIREMENTS	5			
5	PERFORMANCE				5
6	INFRARED REFL	OW CONDIT	<b>FION</b>		
7	PRODUCT QUAL	<b>JFICATION</b>	AND TEST S	SEQUENCE	9
8					

connecto	rs
CE	5

## Aces P/N: 51539-XXXXX series

#### TITLE: 0.5 mm PITCH ZIF BACK FLIP FPC CONN. SMT R/A TYPE

RELEASE DATE: 2015/09/01 REVISION: C

ECN No: ECN-1509013

PAGE: 3 OF 13

## 1 Revision History

Rev.	ECN #	<b>Revision Description</b>	Prepared	Date
1	ECN-1106105	NEW PROJECT SPEC FOR APD1000191	STANLEY	2011.06.07
0	ECN-1112070	NEW RELEASED	STANLEY	2011.12.07
Α	ECN-1206422	MODIFIED CONNECTOR OPERATION	JAMELSEN	2012.06.21
В	ECN-1401128	ADD Working voltage	YANGYANG	2014/01/10
С	ECN-1509013	ADD CONNECTOR OPERATION	ZHOUQUAN	2015/09/01

CES		Aces P/N: 51539-XXXXX series	
TITLE: 0.5 mm PITCH	I ZIF BACK FLI	P FPC CONN. SMT R/A TYPE	
RELEASE DATE: 2015/09/01	REVISION: C	ECN No: ECN-1509013	PAGE: 4 OF 13

## 2 SCOPE

This specification covers performance, tests and quality requirements for 0.5 mm pitch ZIF back flip FPC CONN. SMT D/C R/A type.

## **3 APPLICABLE DOCUMENTS**

EIA-364: ELECTRONICS INDUSTRIES ASSOCIATION

## 4 REQUIREMENTS

4.1 Design and Construction

- 4.1.1 Product shall be of design, construction and physical dimensions specified on applicable product drawing.
- 4.1.2 All materials conform to R.o.H.S. and the standard depends on TQ-WI-140101.

#### 4.2 Materials and Finish

Finish:

- 4.2.1 Contact: High performance copper alloy (Phosphor Bronze)
  - (a) Contact Area: Refer to the drawing.
    - (b) Under plate: Refer to the drawing.
  - (c) Solder area: Refer to the drawing.
- 4.2.2 Housing: Thermoplastic or Thermoplastic High Temp., UL94V-0
- 4.2.3 Actuator: Thermoplastic or Thermoplastic High Temp., UL94V-0
- 4.2.4 Fitting Nail: Copper Alloy, Finish: Refer to the drawing.

4.3 Ratings

- 4.3.1 Working voltage less than 36 volts AC (per pin)
- 4.3.2 Voltage: 50 Volts AC (per pin)
- 4.3.3 Current: DC 0.5 Amperes (per pin)
- 4.3.4 Operating Temperature : -40  $^\circ\!\mathrm{C}$  to +85  $^\circ\!\mathrm{C}$

Aces P/N: 51539-XXXXX series	
TITLE: 0.5 mm PITCH ZIF BACK FLIP FPC CONN. SMT R/A TYPE	
RELEASE DATE: 2015/09/01 REVISION: C ECN No: ECN-1509013 PAGE: 5	DF <b>13</b>

# 5 Performance

## 5.1. Test Requirements and Procedures Summary

ltem	Requirement	Standard			
Examination of Product	Product shall meet requirements of applicable product drawing and specification.	f Visual, dimensional and functional per applicable quality inspection plan.			
	ELECTRICAL				
Item	Requirement	Standard			
Low Level Contact Resistance	60 m Ω Max.(initial)per contact 20 m Ω Max. Change allowed	Mate connectors, measure by dry circuit, 20mV Max., 100mA (EIA-364-23)			
Insulation Resistance	500 M Ω Min.	Unmated connectors, apply 100 V DC between adjacent terminals. (EIA-364-21)			
Dielectric Withstanding Voltage No discharge, flashover or breakdown. Current leakage: 1 mA max.		200 VAC Min. at sea level for 1 minute. Test between adjacent contacts of unmated connectors. (EIA-364-20)			
Temperature rise	30°C Max. Change allowed	Mate connector: measure the temperature rise at rated current until temperature stable. The ambient condition is still air at 25°C (EIA-364-70 METHOD 1,CONDITION 1)			

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## Aces P/N: 51539-XXXXX series

### TITLE: 0.5 mm PITCH ZIF BACK FLIP FPC CONN. SMT R/A TYPE

REVISION: C

RELEASE DATE: 2015/09/01

ECN No: ECN-1509013

PAGE: 6 OF 13

	MECHANICAL						
ltem	Requirement	Standard					
Durability	20 cycles.	The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 25.4 ± 3mm/min. (EIA-364-09)					
FPC Retention Force (Without Lock)	15 gf/pin MIN.	Apply axial pull out force at the speed rate of $25.4 \pm 3$ mm/minute.					
Terminal / Housing Retention Force	50 gf MIN.	Apply axial pull out force at the speed rate of $25.4 \pm 3 \text{ mm/minute}$ . On the terminal assembled in the housing.					
Fitting Nail /Housing Retention Force	50 gf MIN.	Apply axial pull out force at the speed rate of 25.4 ± 3 mm/minute. On the fitting nail assembled in the housing.					
Vibration	1 μs Max.	The electrical load condition shall be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude of 0.76mm (1.52mm maximum total excursion) in frequency between the limits of 10 and 55 Hz. The entire frequency range, from 10 to 55 Hz and return to 10 Hz, shall be traversed in approximately 1 minute. This motion shall be applied for 2 hours in each of three mutually perpendicular directions. (EIA-364-28 Condition I)					
Shock (Mechanical)	1 μs Max.	Subject mated connectors to 50 G's (peak value) half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be 100mA maximum for all contacts. (EIA-364-27, test condition A)					

ACES

## Aces P/N: 51539-XXXXX series

### TITLE: 0.5 mm PITCH ZIF BACK FLIP FPC CONN. SMT R/A TYPE

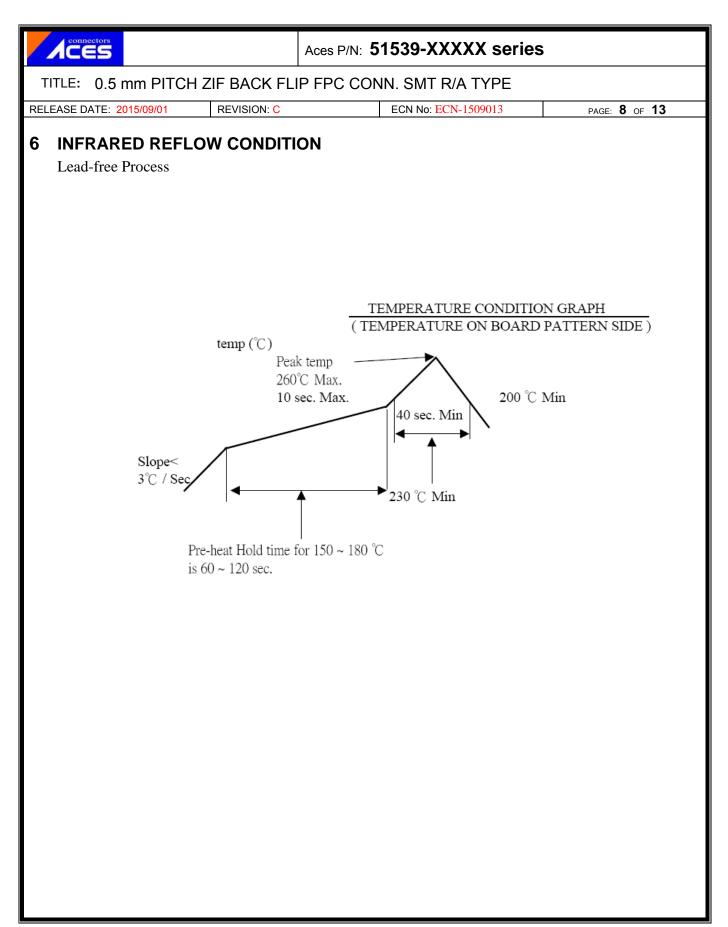
RELEASE DATE: 2015/09/01 REVISION: C

ECN No: ECN-1509013

PAGE: 7 OF 13

	ENVIRONMENTAL	
ltem	Requirement	Standard
Resistance to Reflow Soldering Heat	See Product Qualification and Test Sequence Group 10 <b>(Lead Free)</b> No deformation of components affecting performance.	Pre Heat : 150℃~180℃, 60~120sec. Heat : 230℃ Min., 40sec Min. Peak Temp. : 260℃ Max, 10sec Max. Cycles : 2
Hand Soldering Temperature Resistance	Appearance: No damage	T≧350°C, 3sec at least
Thermal Shock	See Product Qualification and Test Sequence Group 4	Mate module and subject to follow condition for 5 cycles. 1 cycles: -55 +/-3 °C, 30 minutes +85 +/-3 °C, 30 minutes (EIA-364-32, test condition I)
Humidity	See Product Qualification and Test Sequence Group 4	Mated Connector 40°C, 90~95% RH, 96 hours. (EIA-364-31,Condition A, Method II)
Temperature life	See Product Qualification and Test Sequence Group 5	Subject mated connectors to temperature life at 85℃ for 96 hours. (EIA-364-17, Test condition A)
Salt Spray (Only For Gold Plating)	See Product Qualification and Test Sequence Group 6	Subject mated/unmated connectors to 5% salt-solution concentration, 35°C (I) Gold flash for 8 hours (II) Gold plating 5 u" for 96 hours. (EIA-364-26)
Solder ability	Tin plating: Solder able area shall have minimum of 95% solder coverage. Gold plating: Solder able area shall have minimum of 75% solder coverage.	And then into solder bath, Temperature at 245 ±5℃, for 4-5 sec. (EIA-364-52)

Note. Flowing Mixed Gas shell be conduct by customer request.



TLE: 0.5 mm PITCH ZIF BACK FLIP	P FPC	CON	IN. S	MT R	/A TY	ΈE				
EASE DATE: 2015/09/01 REVISION: C			ECN	No: EC	N-1509(	)13		PA	AGE: <b>9</b>	OF <b>13</b>
PRODUCT QUALIFICATION AN	D TE	EST S	BEQL	JENC	E					
Test or Examination	1	2	3	4	Test ( 5	Group	7	8	9	10
	1	4	5	_		quence		0	,	10
Examination of Product					1 \ 6	_	-		1	1
Low Level Contact Resistance		1 • 3	1 • 4	2 \ 10					3	1
Insulation Resistance				3 \ 9	3 \ 8				5	
Dielectric Withstanding Voltage				4 \ 8	4 \ 7					
Temperature rise	1									
Durability		2								
Vibration			2							
Shock (Mechanical)			3							
Thermal Shock				5						
Humidity				6						
Temperature life					5					
Salt Spray(Only For Gold Plating)						3				
Solder ability							1			
Terminal / Housing Retention Force								1		
Fitting Nail /Housing Retention Force								2		
Resistance to Soldering Heat									2	
Hand Soldering Temperature Resistance										2
Sample Size	2	4	4	4	4	4	2	4	4	4

